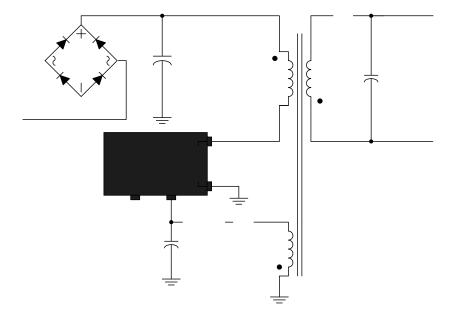
device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please

email any questions regarding the system integration to Fairchild questions@onsemi.com.





Application Circuit



Pin Configuration

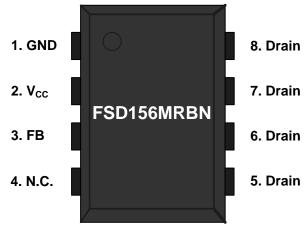


Figure 3. Pin Configuration (Top View)

Pin Definitions

Pin # Name Description

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit	
V_{DS}	Drain Pin Voltage	Drain Pin Voltage			650	V
V _{CC}	V _{CC} Pin Voltage				26	V
V_{FB}	Feedback Pin Voltage			- 0.3	10.0	V
I _{DM}	Drain Current Pulsed				4	Α
	Continuous Switching Drain Current ⁽⁶⁾ T _C =25 C T _C =100 C		T _C =25 C		1.9	Α
I _{DS}				1.27	Α	
E _{AS}	Single Pulsed Avalance	che Energy ⁽⁷⁾			190	mJ
P _D	Total Power Dissipatio	Dissipation (T _C =25 C) ⁽⁸⁾			1.5	W
+	Maximum Junction Temperature			150	С	
T_J	Operating Junction Temperature ⁽⁹⁾			- 40	+125	С
T _{STG}	Storage Temperature			- 55	+150	С
EOD	Electrostatic	Human Body Model, JESD22-A114			5	1.57
ESD	Discharge Capability Charged Device Mo		odel, JESD22-C101		2	kV

Notes:

6. Repetitive peak switching current when the inductive load is assumed: Limited by maximum duty ($D_{MAX}=0.73$)

Electrical Characteristics

 $T_J = 25$ C unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
SenseFET	Section			•		
BV _{DSS}	Drain-Source Breakdown Voltage	V _{CC} = 0V, I _D = 250 A	650			V
I _{DSS}	Zero-Gate-Voltage Drain Current	V _{DS} = 650V, T _A = 25 C			250	Α
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =1A		1.8	2.2	
C _{ISS}	Input Capacitance ⁽¹²⁾	$V_{DS} = 25V, V_{GS} = 0V, f=1MHz$		515		pF
Coss	Output Capacitance ⁽¹²⁾	$V_{DS} = 25V, V_{GS} = 0V, f=1MHz$		75		pF
t _r	Rise Time	$V_{DS} = 325V$, $I_D = 4A$, $R_G = 25$		26		ns
t _f	Fall Time	$V_{DS} = 325V$, $I_D = 4A$, $R_G = 25$		25		ns
t _{d(on)}	Turn-On Delay	$V_{DS} = 325V$, $I_D = 4A$, $R_G = 25$		14		ns
$t_{\text{d(off)}}$	Turn-Off Delay	$V_{DS} = 325V$, $I_D = 4A$, $R_G = 25$		32		ns
Control Sec	ction					
f _S	Switching Frequency ⁽¹²⁾	V _{CC} = 14V, V _{FB} = 4V	61	67	73	kHz
f _S	Switching Frequency Variation ⁽¹²⁾	- 25 C < T _J < 125 C		±5	±10	%
D _{MAX}	Maximum Duty Ratio	V _{CC} = 14V, V _{FB} = 4V	61	67	73	%
D _{MIN}	Minimum Duty Ratio	V _{CC} = 14V, V _{FB} = 0V			0	%
I _{FB}	Feedback Source Current	V _{FB} = 0	65	90	115	Α

 V_{START}

UVLO Threshold Voltage

Electrical Characteristics (Continued)	5
T_J	7
IJ	
	(
	2
	=
	2
	=
	•
	2
	7
	-
	7
	7
	-
	1
	-
	-
	0

Typical Performance Characteristics

Characteristic graphs are normalized at T_A=25°C.



Typical Performance Characteristics Characteristic graphs are normalized at T _A	FSD156MRBN
	MXUN
	- Green
	-Mode F
	- Green-Mode Fairchild Power Switch (FPS IM)
	Power S
	witch (F
	PS M

4. Protection Circuits: The FSD156MRBN has several self-protective functions, such as Overload Protection (OLP), Abnormal Over-Current Protection (AOCP), Output-Short Protection (OSP), Over-Voltage Protection (OVP), and Thermal Shutdown (TSD). All the protections are implemented as auto-restart. Once the fault condition is detected, switching is terminated and the SenseFET remains off. This causes V_{CC} to fall. When V_{CC} falls to the Under-Voltage Lockout (UVLO) stop voltage of 7.5V, the protection is reset and the startup circuit charges the V_{CC} capacitor. When V_{CC} reaches the start voltage of 12.0V, the FSD156MRBN resumes normal operation. If the fault condition is not removed, the SenseFET remains off and V_{CC} drops to

4.3. Output-Short Protection (OSP): If the output is shorted, steep current with extremely high di/dt can flow through the SenseFET during the minimum turnon time. Such a steep current brings high-voltage stress on the drain of the SenseFET when turned off. To protect the device from this abnormal condition, OSP is included. It is comprised of detecting V_{FB} and SenseFET turn-on time. When the V_{FB} is higher than 2.0V and the SenseFET turn-on time is lower than 1.0µs, this condition is recognized as an abnormal error and PWM switching shuts down until V_{CC} reaches V_{START} again. An abnormal condition output short is shown in Figure 22.

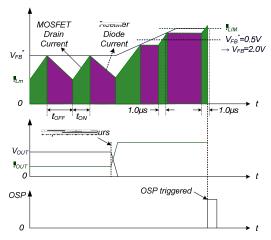


Figure 22. Output-Short Protection

4.4 Over-Voltage Protection (OVP): If the secondary-side feedback circuit malfunctions or a solder defect causes an opening in the feedback path, the current through the opto-coupler transistor becomes almost zero. Then V_{FB} climbs up in a similar manner to the overload situation, forcing the preset maximum current to be supplied to the SMPS until the overload protection is triggered. Because more energy than required is provided to the output, the output voltage may exceed the rated voltage before

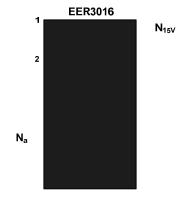
Typical Application Circuit

Application	Input Voltage	Rated Output	Rated Power
LCD Monitor Power Supply	85 ~ 265V _{AC}	5.0V(2A) 14.0V(1.3A)	28.2W

Key Design Notes

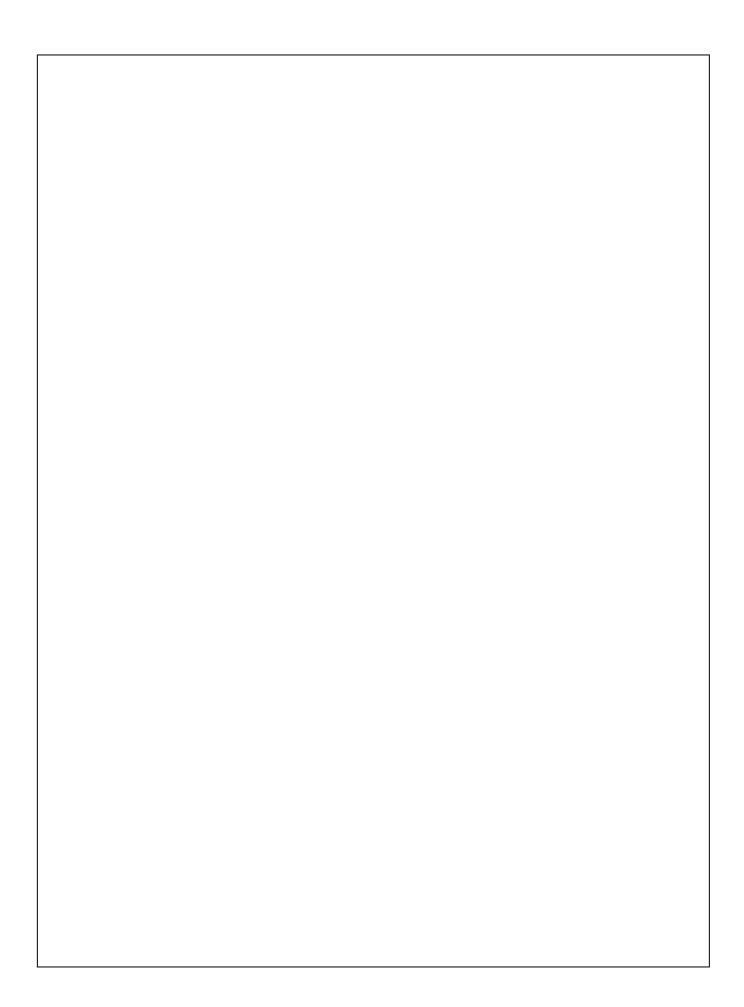
- 1. The delay for overload protection is designed to be about 30ms with C105 (8.2nF). OLP time between 39ms (12nF) and 46ms (15nF) is recommended.
- 2. The SMD-type capacitor (C106) must be placed as close as possible to the V_{CC} pin to avoid malfunction by

Transformer



Bill of Materials

Part #	Value	Note	Part #	Value	Note
	Fuse			Capacitor	
F101	250V 2A		C101	220nF/275V	Box (Pilkor)
	NTC		C102	150nF/275V	Box (Pilkor)
NTC101	5D-9	DSC	C103	100 F/400V	Electrolytic (SamYoung)
	Resistor		C104	3.3nF/630V	Film (Sehwa)
R101	1.5M , J	1W	C105	15nF/100V	Film (Sehwa)
R103	43k , J	1W	C106	100nF	SMD (2012)
R201	1.5k , F	1/4W, 1%	C107	47 F/50V	Electrolytic (SamYoung)
R202	1.0k , F	1/4W, 1%	C201	820 F/25V	Electrolytic (SamYoung)



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